

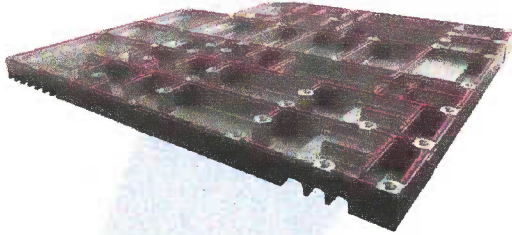
**SNL60-RXP Form-In-Place**

A rapid cure, silver/aluminum-filled silicone elastomer Form-In-Place gasket material.

Laird Technologies introduces its newest line of FIP products—EMI Sentry. These Form-In-Place pastes are extremely fast curing with reliable shielding effectiveness and strength

Laird Technologies' Form-In-Place is an automated system for dispensing conductive elastomer EMI shielding and grounding gaskets onto metal or plastic substrates. This product is particularly ideal for basestations, PDAs, PC cards, radios, mobile phones, as well as many other cast or plastic enclosures and packaged electronic assemblies.

**TYPICAL VALUES**



\* does not represent actual value

	TEST METHOD	UNITS	SNL60-RXP
Elastomer			Silicone
Filler			Silver/Aluminum
<b>ELECTRICAL PROPERTIES</b>			
Volume Resistivity		ohm-cm	0.003
Shielding Effectiveness	MIL-DTL-83528C		
200 MHz to 10 GHz	Para.4.5.12	dB	>100
<b>PHYSICAL PROPERTIES</b>			
Hardness	ASTMD2240	Shore A	60
Tensile Strength	ASTMD412	kPa	850
Tensile Elongation	ASTMD412	%	140
Density (cured)	ASTMD792	g/cm <sup>3</sup>	2.1
Density (uncured)	LT-FIP-CLE-09	g/cm <sup>3</sup>	1.8
Compression Set	ASTMD395	%	10
Adhesion Strength (AI)	LT-FIP-CLE-03	N/cm <sup>2</sup>	140
Compression-Deflection(a)	LT-FIP-CLE-07		
at 20% compression		lb/in	1.9
at 40% compression		lb/in	8.3
Temperature Range		°C	-50°C to 125°C
UL rating	UL-94		V0
<b>CURING REQUIREMENTS</b>			
Cure Conditions		15°C to 40°C, 50% relative	
At 22°C and 50% RH	LT-FIP-CLE-14		
Time before handling			1 hour
Full Cure			24 hours

(a) Compression-deflection bead size 0.60 mm (H) x 0.75 mm (W)

REV 07/02/09



